

**FEE TRANSMITTAL**

Electronic Version v08

Stylesheet Version v08.0

**Title of  
Invention****[METAL BONDING METHOD FOR SEMICONDUCTOR CIRCUIT  
COMPONENTS EMPLOYING PRESCRIBED FEEDS OF METAL BALLS]**

Application Number :

Date :

First Named Applicant: Mr. Cheng-Chieh Yang

Attorney Docket Number: 11053-US-PA

**TOTAL FEE AUTHORIZED \$ 385**

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as small entity

**BASIC FILING FEE**

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	2001	385	385
Subtotal For Basic Filing Fees: \$ 385			

**EXTRA CLAIM FEES**

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 10	0	2202	9	0
Independent Claims : 1	0	2201	43	0
Subtotal For Extra Claims Fees: \$ 0				

**AUTHORIZED BILLING INFORMATION****The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:**

Credit account number: 1000  
Expiration Date (YYYYMMDD): 2006-10-31  
Authorized name: LEE, HUAI-LU  
Billing address: 99999